

# Moving Towards Integrated Circuits

History and Fabrication

# Transistor History

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- First transistors were hybrid devices made from germanium and operated in a vacuum tube (1947).
- The first transistor radio (by Regency Division of IDEA) was made from 4 transistors and required a 22.5 V battery (1954).
- The bipolar junction transistor was developed in the late 1950s (still hybrid).
- The movement to monolithic devices came in the 1960s with the dawn of silicon microfabrication.
- BJTs were the earliest transistors and are current-controlled devices. They can carry larger currents and perform well at high frequencies.
- MOSFETs are voltage controlled devices. They are symmetrical, can operate at low power, can be made smaller, and have near infinite input resistance.

# Transistors

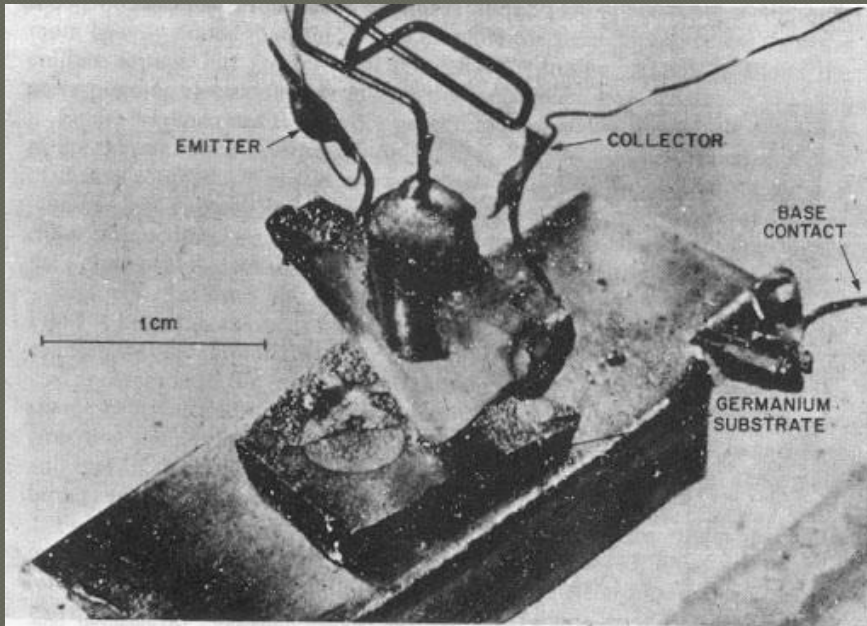


Fig. 1 The first transistor.<sup>1</sup>

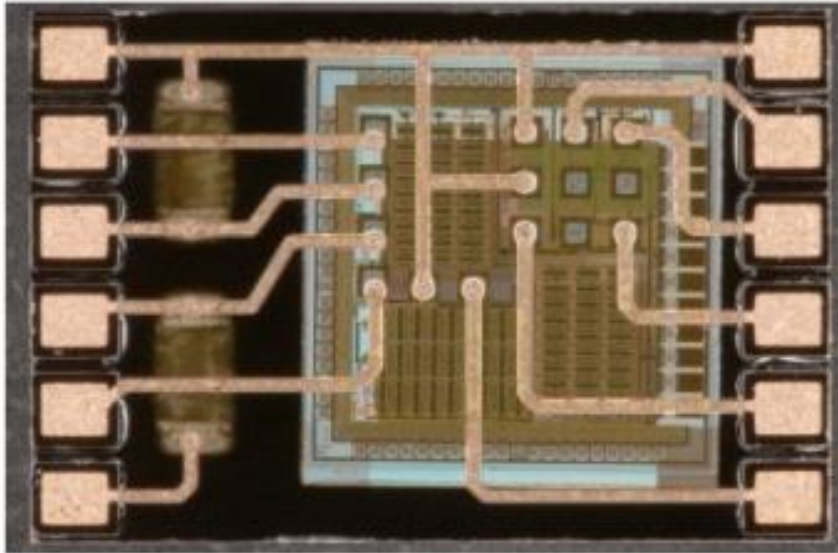
Bell Labs Engineers: Shockley, Brattain and Bardeen invented the point-contact transistor in 1947 and the hybrid BJT in 1948

Transistors were originally manufactured from Germanium.

Silicon became the material of the future because of its high operating temperature, inert material qualities, and cost.

# Transistors

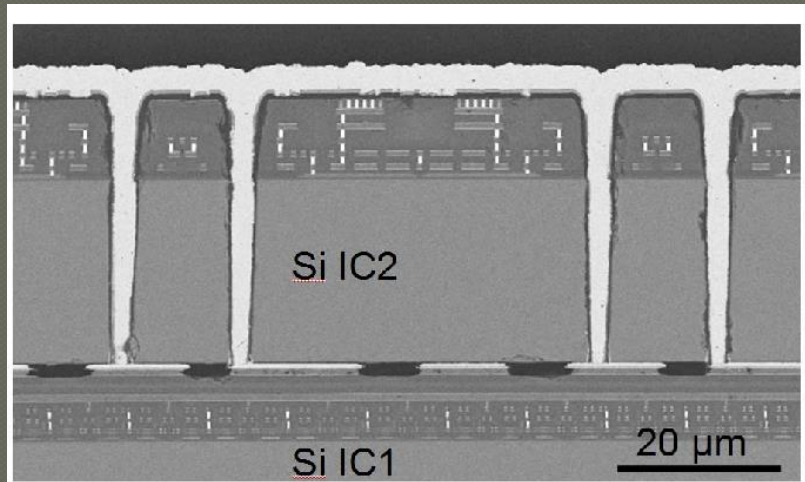
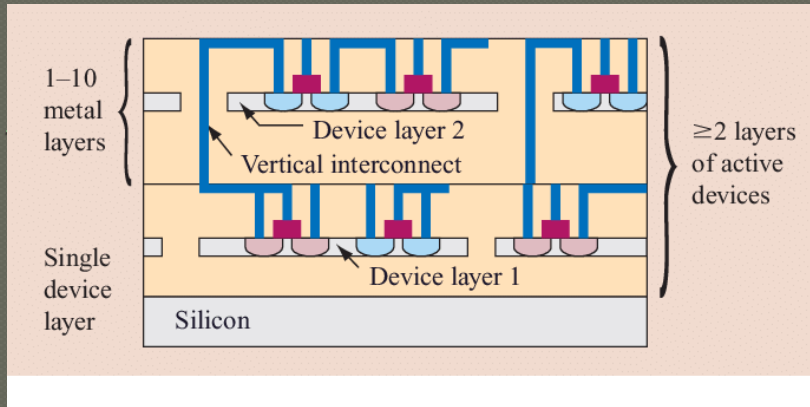
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Silicon fabrication processes allowed for smaller feature sizes and increased density of transistors per unit area.

Transistor are small, but contact pads, resistors and capacitors take up a lot of space.

# Transistors



Just like in cities, when we run out of space, we go vertical!

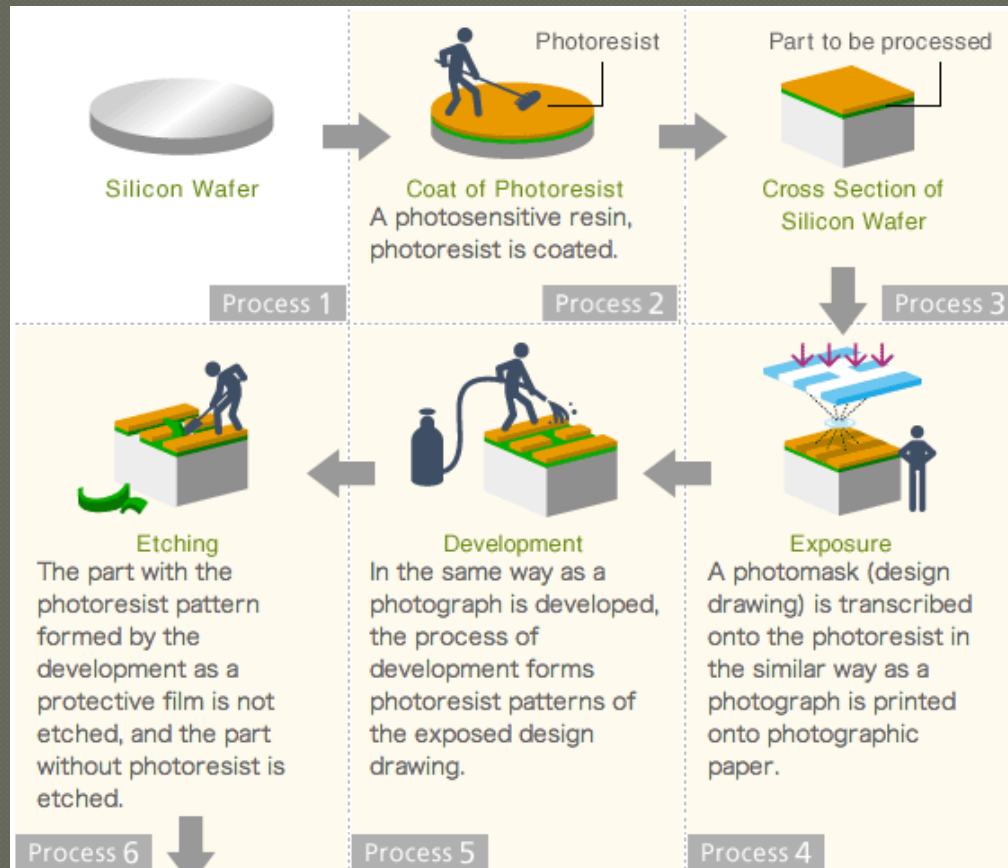
# Semiconductor Fabrication

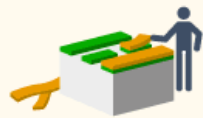
- Fabrication is done in a largely automated process to reduce manufacturing issues related to humans coming in and out of the plant.



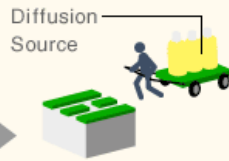


# General Process





**Removal of Photoresist**  
After processing, used photoresist is removed.



**Coat of an Agent for Diffusing Dopants**  
An agent that diffuses dopants is coated.



**Formation of Semiconductor Area**  
After the diffusing agent has been coated, a semiconductor area is created by high-temperature baking.



**Formation of Wiring**  
Processing including photoresist coating, exposure, development, and etching is carried out and form wiring which is made of aluminum or copper.



**Formation of Integrated Circuits**  
By repeating these processes, a variety of different types of circuits and then integrated circuits are made.



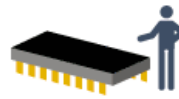
**Completion of an Integrated Circuit on the Wafer**  
Integrated circuits cover the wafer processed by microprocess technology.



**Dicing a Wafer**  
The wafer is diced into chips.



**IC Chip**  
Each piece of the diced wafer is an IC chip.



**Completion of LSI**

# General Process



# Health and Environmental Impacts of Manufacturing

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- Many chemicals associated with semiconductor fabrication are toxic to humans and to the environment.
- Water usage is a huge factor as well.
- A typical facility uses 240,000 kW-hrs of electricity and over 2 million gallons of water every day. (The average person uses about 100 gallons of water a day).
- Chemicals require disposal mechanisms to protect the water table.
- Not to mention issues with disposal of actual circuits after their useful life ends (arsenic, gallium and heavy metals leach out in the environment)